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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Yoshimasa KAWASE

Title: WAFER HEAT-TREATMENT SYSTEM AND WAFER HEAT-TREATMENT METHOD

Appl. No.: 10/066,783

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Art Unit: 3749

REPLY UNDER 37 CFR 1.111

Mail Stop NON-FEE AMENDMENT  
Commissioner for Patents  
PO Box 1450  
Alexandria, Virginia 22313-1450

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Sir:

This communication is responsive to the Non-Final Office Action dated December 12, 2003, concerning the above-referenced patent application.

The claims are listed in the listing of claims which begins on page 2 of this document.

**Remarks/Arguments** begin on page 4 of this document.